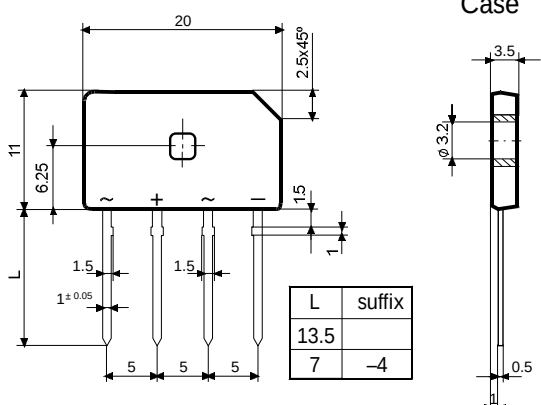


2. Amp. Glass Passivated Bridge Rectifier

<p>Dimensions in mm.</p>  <p>Plastic Case</p> <p>• Mounting Instructions</p> <ul style="list-style-type: none"> • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm. 	<p>Voltage 100 to 1000 V.</p> <p>Current 2.0 A.</p> <p>HYPERECTIFIER®</p> <p>• Glass Passivated Junction Chips.</p> <ul style="list-style-type: none"> • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • The plastic material carries U/L recognition 94 V-O.
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Maximum Ratings, according to IEC publication No. 134

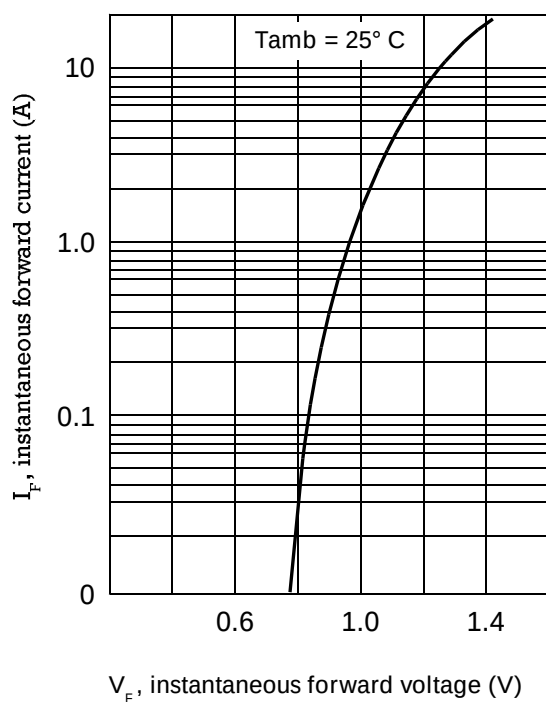
		FBI2B 5S2	FBI2D 5S2	FBI2F 5S2	FBI2J 5S2	FBI2L 5S2	FBI2M 5S2
V_{RRM}	Peak Recurrent Reverse Voltage (V)	100	200	300	600	900	1000
V_{RMS}	Maximum RMS Voltage (V)	70	140	210	420	630	700
V_R	Recommended Input Voltage (V)	40	80	125	250	380	500
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	4.5 A at 65 °C 2.0 A at 25 °C					
I_{FRM}	Recurrent peak forward current	15 A					
I_{FSM}	10 ms. peak forward surge current	100 A					
I^2t	I^2t value for fusing (t = 10 ms)	50 A ² sec					
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	1500 V					
T_j	Operating temperature range	– 40 to + 150 °C					
T_{stg}	Storage temperature range	– 40 to +150 °C					

Electrical Characteristics at Tamb = 25°C

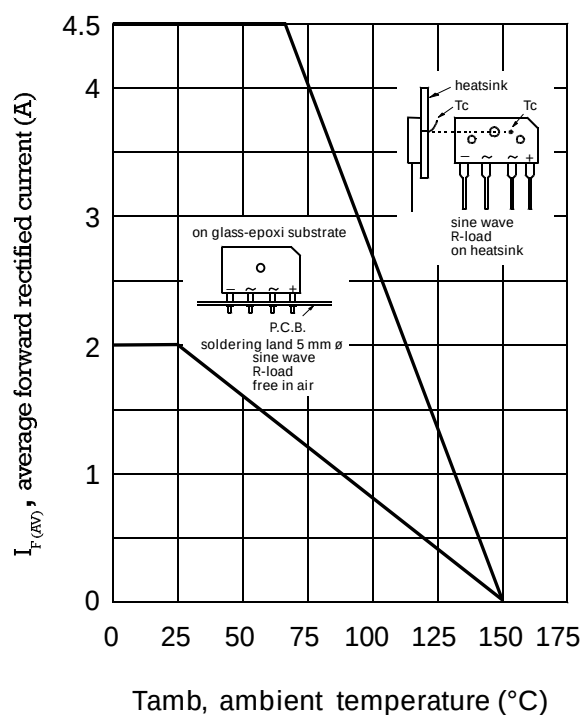
V_F	Max. forward voltage drop per element at $I_F = 3$ A	1.1 V
I_R	Max. reverse current per element at V_{RRM}	5 μA
$R_{th(j-c)}$ $R_{th(j-a)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink. Junction-Ambient. Without Heatsink.	12 °C/W 40 °C/W

Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

